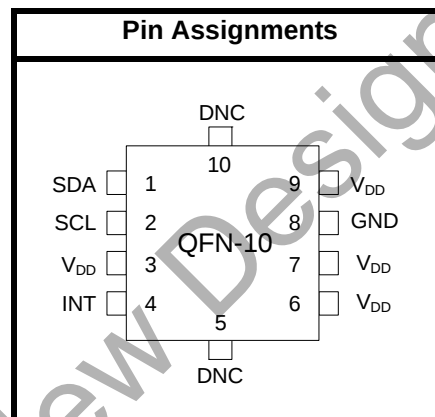


UV INDEX AND AMBIENT LIGHT SENSOR IC WITH I²C INTERFACE

Features

- Integrated UV index sensor
 - Digital UV Index register that can be read through I²C interface
 - Factory calibration to address part-to-part variation
- Integrated ambient light sensor
 - 100 mlx resolution possible, allowing operation under dark glass
 - 1 to 128 klx dynamic range possible across two ADC range settings
 - Accurate lux measurements with IR correction algorithm
- Industry's lowest power consumption
 - 1.71 to 3.6 V supply voltage
 - < 500 nA standby current
 - Internal and external wake support
 - Built-in voltage supply monitor and power-on reset controller
- I²C Serial communications
 - Up to 3.4 Mbps data rate
 - Slave mode hardware address decoding
- Small-outline 10-lead 2x2 mm QFN
- Temperature Range
 - -40 to +85 °C



Applications

- Fitness/health electronics
- Smart watches
- Smartphone handsets
- Tablets
- Portable consumer electronics
- Display-backlighting control

Description

The Si1132 is a low-power, ultraviolet (UV) index, and ambient light sensor with I²C digital interface and programmable-event interrupt output. This sensor IC includes an analog-to-digital converter, integrated high-sensitivity visible and infrared photodiodes, and digital signal processor. The Si1132 offers excellent performance under a wide dynamic range and a variety of light sources including direct sunlight. The Si1132 can also work under dark glass covers. The photodiode response and associated digital conversion circuitry provide excellent immunity to artificial light flicker noise and natural light flutter noise. The Si1132 devices are provided in a 10-lead 2x2 mm QFN package and are capable of operation from 1.71 to 3.6 V over the -40 to +85 °C temperature range.

Si1132

Functional Block Diagram

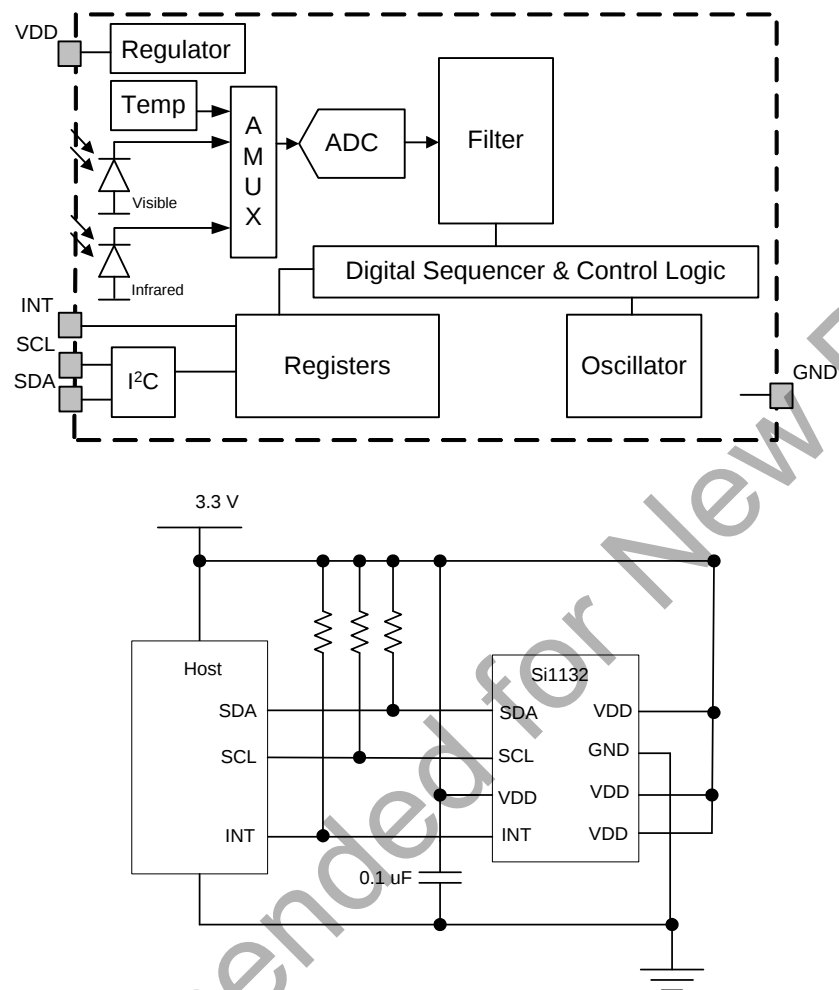


Figure 1. Si1132 Application

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1. Electrical Specifications

1.1. Performance Tables

Table 1. Recommended Operating Conditions

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
V _{DD} Supply Voltage	V _{DD}		1.71	—	3.6	V
V _{DD} OFF Supply Voltage	V _{DD_OFF}	OFF mode	−0.3		1.0	V
V _{DD} Supply Ripple Voltage		V _{DD} = 3.3 V 1 kHz–10 MHz	—	—	50	mVpp
Operating Temperature	T		−40	25	85	°C
SCL, SDA, Input High Logic Voltage	I ² C _{VIH}		V _{DD} × 0.7	—	V _{DD}	V
SCL, SDA Input Low Logic Voltage	I ² C _{VIL}		0	—	V _{DD} × 0.3	V
Operation under Direct Sunlight	E _{dc}		—	—	128	klx
Start-Up Time		V _{DD} above 1.71 V	25	—	—	ms

Table 2. Performance Characteristics¹

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
I _{DD} OFF Mode	I _{off}	V _{DD} < V _{DD_OFF} (leakage from SCL, SDA, and INT not included)	—	240	1000	nA
I _{DD} Standby Mode	I _{sb}	No ALS Conversions No I ² C Activity V _{DD} = 1.8 V	—	150	500	nA
I _{DD} Standby Mode	I _{sb}	No ALS Conversions No I ² C Activity V _{DD} = 3.3 V	—	1.4	—	μA
I _{DD} Actively Measuring	I _{active}	V _{DD} = 3.3 V	—	4.3	5.5	mA
INT, SCL, SDA Leakage Current		V _{DD} = 3.3 V	−1	—	1	μA
Actively Measuring Time ²		UV or ALS VIS + ALS IR	—	285	—	μs

Notes:

1. Unless specifically stated in "Conditions", electrical data assumes ambient light levels < 1 klx.
2. Represents the time during which the device is drawing a current equal to I_{active} for power estimation purposes. Assumes default settings.

Table 2. Performance Characteristics¹ (Continued)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Visible Photodiode Response		Sunlight ALS_VIS_ADC_GAIN=0 VIS_RANGE=0	—	0.282	—	ADC counts/lux
		2500K incandescent bulb ALS_VIS_ADC_GAIN=0 VIS_RANGE=0	—	0.319	—	ADC counts/lux
		“Cool white” fluorescent ALS_VIS_ADC_GAIN=0 VIS_RANGE=0	—	0.146	—	ADC counts/lux
		Infrared LED (875 nm) ALS_VIS_ADC_GAIN=0 VIS_RANGE=0	—	8.277	—	ADC counts. m ² /W
Small Infrared Photodiode Response		Sunlight ALS_IR_ADC_GAIN=0 IR_RANGE=0	—	2.44	—	ADC counts/lux
		2500K incandescent bulb ALS_IR_ADC_GAIN=0 IR_RANGE=0	—	8.46	—	ADC counts/lux
		“Cool white” fluorescent ALS_IR_ADC_GAIN=0 IR_RANGE=0	—	0.71	—	ADC counts/lux
		Infrared LED (875 nm) ALS_IR_ADC_GAIN=0 IR_RANGE=0	—	452.38	—	ADC counts. m ² /W
Visible Photodiode Noise		All gain settings	—	7	—	ADC counts RMS
Small Infrared Photodiode Noise		All gain settings	—	1	—	ADC counts RMS
Notes: 1. Unless specifically stated in "Conditions", electrical data assumes ambient light levels < 1 klx. 2. Represents the time during which the device is drawing a current equal to I_{active} for power estimation purposes. Assumes default settings.						

Table 2. Performance Characteristics¹ (Continued)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Visible Photodiode Offset Drift		VIS_RANGE=0 ALS_VIS_ADC_GAIN=0 ALS_VIS_ADC_GAIN=1 ALS_VIS_ADC_GAIN=2 ALS_VIS_ADC_GAIN=3 ALS_VIS_ADC_GAIN=4 ALS_VIS_ADC_GAIN=5 ALS_VIS_ADC_GAIN=6 ALS_VIS_ADC_GAIN=7	—	—0.3 —0.11 —0.06 —0.03 —0.01 —0.008 —0.007 —0.008	—	ADC counts/ °C
Small Infrared Photodiode Offset Drift		IR_RANGE=0 IR_GAIN=0 IR_GAIN=1 IR_GAIN=2 IR_GAIN=3	—	—0.3 —0.06 —0.03 —0.01	—	ADC counts/ °C
SCL, SDA, INT Output Low Voltage	V _{OL}	I = 4 mA, V _{DD} > 2.0 V I = 4 mA, V _{DD} < 2.0 V	— —	— —	V _{DD} × 0.2 0.4	V V
Temperature Sensor Offset		25 °C	—	11136	—	ADC counts
Temperature Sensor Gain			—	35	—	ADC counts/ °C
Notes: 1. Unless specifically stated in "Conditions", electrical data assumes ambient light levels < 1 klx. 2. Represents the time during which the device is drawing a current equal to I _{active} for power estimation purposes. Assumes default settings.						

Table 3. I²C Timing Specifications

Parameter	Symbol	Min	Typ	Max	Unit
Clock Frequency	f _{SCL}	95	—	3400	KHz
Clock Pulse Width Low	t _{LOW}	160	—	—	ns
Clock Pulse Width High	t _{HIGH}	60	—	—	ns
Rise Time	t _R	10	—	40	ns
Fall Time	t _F	10	—	40	ns
Start Condition Hold Time	t _{HD.STA}	160	—	—	ns
Start Condition Setup Time	t _{SU.STA}	160	—	—	ns
Input Data Setup Time	t _{SU.DAT}	10	—	—	ns
Input Data Hold Time	t _{HD.DAT}	0	—	—	ns
Stop Condition Setup Time	t _{SU.STO}	160	—	—	ns

Table 4. Absolute Maximum Limits

Parameter	Test Condition	Min	Typ	Max	Unit
V _{DD} Supply Voltage		−0.3	—	4	V
Operating Temperature		−40	—	85	°C
Storage Temperature		−65	—	85	°C
INT, SCL, SDA Voltage	at V _{DD} = 0 V, T _A < 85 °C	−0.5	—	3.6	V
ESD Rating	Human Body Model	—	—	2	kV
	Machine Model	—	—	225	V
	Charged-Device Model	—	—	2	kV

1.2. Typical Performance Graphs

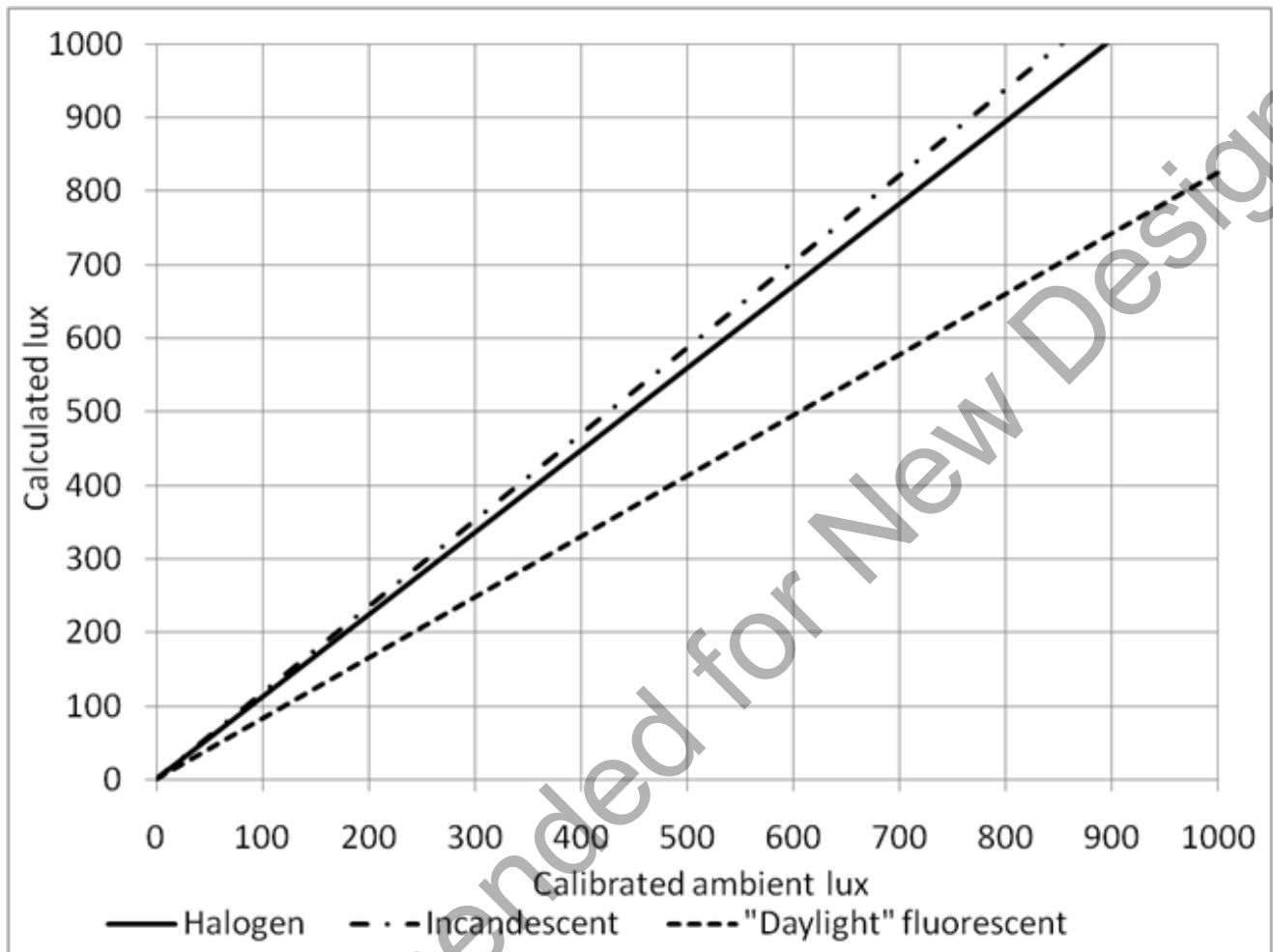


Figure 2. ALS Variability with Different Light Sources

2. Functional Description

2.1. Introduction

The Si1132 is a UV index and ambient light sensor whose operational state is controlled through registers accessible through the I²C interface. The host can command the Si1132 to initiate on-demand UV index sensing or ambient light sensing. The host can also place the Si1132 in an autonomous operational state where it performs measurements at set intervals and interrupts the host after each measurement is completed. This results in an overall system power saving allowing the host controller to operate longer in its sleep state instead of polling the Si1132. For more details, refer to "AN498: Si114x Designer's Guide".

2.2. Ambient Light

The Si1132 has photodiodes capable of measuring both visible and infrared light. However, the visible photodiode is also influenced by infrared light. The measurement of illuminance requires the same spectral response as the human eye. If an accurate lux measurement is desired, the extra IR response of the visible-light photodiode must be compensated. Therefore, to allow the host to make corrections to the infrared light's influence, the Si1132 reports the infrared light measurement on a separate channel. The separate visible and IR photodiodes lend themselves to a variety of algorithmic solutions. The host can then take these two measurements and run an algorithm to derive an equivalent lux level as perceived by a human eye. Having the IR correction algorithm running in the host allows for the most flexibility in adjusting for system-dependent variables. For example, if the glass used in the system blocks visible light more than infrared light, the IR correction needs to be adjusted.

If the host is not making any infrared corrections, the infrared measurement can be turned off in the CHLIST parameter.

By default, the measurement parameters are optimized for indoor ambient light levels where it is possible to detect light levels as low as 6 lx. For operation under direct sunlight, the ADC can be programmed to operate in a high signal operation so that it is possible to measure direct sunlight without overflowing the 16-bit result.

For low-light applications, it is possible to increase the ADC integration time. Normally, the integration time is 25.6 μ s. By increasing this integration time to 410 μ s, the ADC can detect light levels as low as 1 lx. The ADC can be programmed with an integration time as high as 3.28 ms, allowing measurement to 100 mlx light levels. The ADC integration time for the Visible Light Ambient measurement can be programmed independently of the ADC integration time of the Infrared Light Ambient measurement. The independent ADC parameters allow operation under glass covers having a higher transmittance to Infrared Light than Visible Light.

When operating in the lower signal range, or when the integration time is increased, it is possible to saturate the ADC when the ambient light suddenly increases. Any overflow condition is reported in the RESPONSE register, and the corresponding data registers report a value of 0xFFFF. Based on either of these two overflow indicators, the host can adjust the ADC sensitivity. However, the overflow condition is not sticky. If the light levels return to a range within the capabilities of the ADC, the corresponding data registers begin to operate normally. The RESPONSE register will continue to hold the overflow condition until a NOP command is received. Even if the RESPONSE register has an overflow condition, commands are still accepted and processed.

The Si1132 can initiate ALS measurements either when explicitly commanded by the host or periodically through an autonomous process. Refer to "3. Operational Modes" on page 15 for additional details of the Si1132's Operational Modes.



Figure 3. Photodiode Spectral Response to Visible and Infrared Light (Indicative)

2.3. Ultraviolet (UV) Index

The UV Index is a number linearly related to the intensity of sunlight reaching the earth and is weighted according to the CIE Erythral Action Spectrum as shown in Figure 4. This weighting is a standardized measure of human skin's response to different wavelengths of sunlight from UVB to UVA. The UV Index has been standardized by the World Health Organization and includes a simplified consumer UV exposure level as shown in Figures 5 and 6.

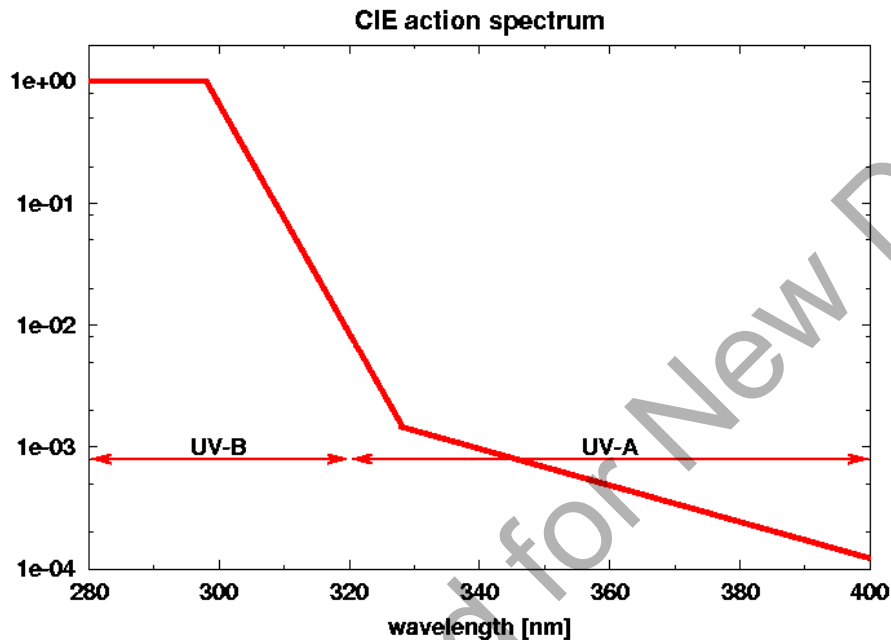


Figure 4. CIE Erythral Action Spectrum



Figure 5. UV Index Scale



Figure 6. UV Levels

To enable UV reading, set the EN_UV bit in CHLIST, and configure UCOEF [0:3] to the default values of 0x7B, 0x6B, 0x01, and 0x00. Also set the VIS_RANGE and IR_RANGE bits. If the sensor will be under an overlay that is not 100% transmissive to sunlight, contact Silicon Labs for more information on adjusting these coefficients.

Typically, after 285 μ s, AUX_DATA will contain a 16-bit value representing 100 times the sunlight UV Index. Host software must divide the results from AUX_DATA by 100.

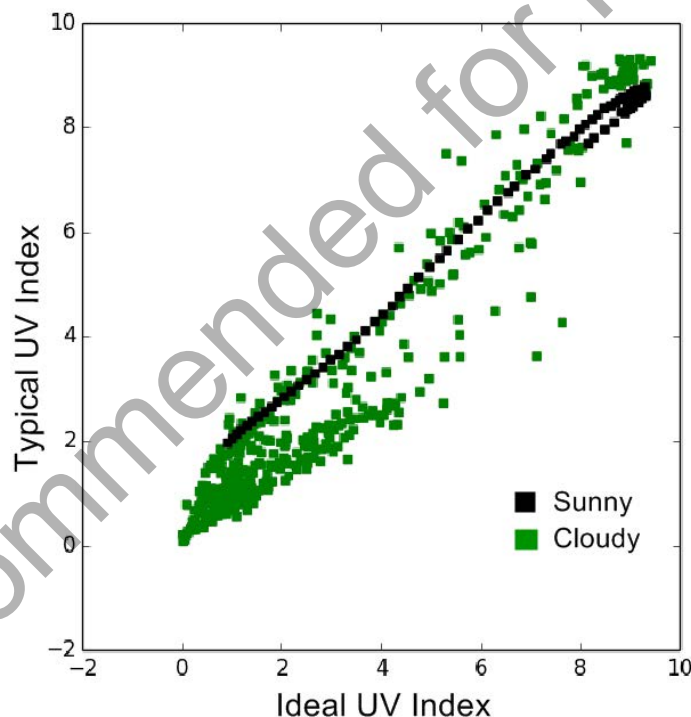
The accuracy of UV readings can be improved by using calibration parameters that are programmed into the Si1132 at Silicon Labs' production facilities to adjust for normal part-to-part variation. The calibration parameters are recovered from the Si1132 by writing Command Register @ address 0x18 with the value 0x12.

When the calibration parameters are recovered, they show up at I²C registers 0x22 to 0x2D. These are the same registers used to report the VIS, IR, and AUX measurements.

The use of calibration parameters is documented in the file, Si114x_functions.h, which is part of the Si114x Programmer's Toolkit example source code and is downloadable from Silabs.com. The host code is expected to allocate memory for the Si114x_CAL_S structure. The Si114x_calibration routine will then fill it up with the appropriate values.

Once the calibration parameters have been recovered the routine Si114x_set_ucoef is used to modify the default values that go into the UCOEF0 to UCOEF3 UV configuration registers to remove normal part-to-part variation.

The typical calibrated UV sensor response vs. calculated ideal UV Index is shown in Figure 7 for a large database of sunlight spectra from cloudy to sunny days and at various angles of the sun/time of day.



**Figure 7. Calibrated UV Sensor Response vs. Calculated Ideal UV Index
(AUX_DATA Measurement / 100)**

2.4. Host Interface

The host interface to the Si1132 consists of three pins:

- SCL
- SDA
- INT

SCL and SDA are standard open-drain pins as required for I²C operation.

The Si1132 asserts the INT pin to interrupt the host processor. The INT pin is an open-drain output. A pull-up resistor is needed for proper operation. As an open-drain output, it can be shared with other open-drain interrupt sources in the system.

For proper operation, the Si1132 is expected to fully complete its Initialization Mode prior to any activity on the I²C. The INT, SCL, and SDA pins are designed so that it is possible for the Si1132 to enter the Off Mode by software command without interfering with normal operation of other I²C devices on the bus.

The Si1132 I²C slave address is 0x60. The Si1132 also responds to the global address (0x00) and the global reset command (0x06). Only 7-bit I²C addressing is supported; 10-bit I²C addressing is not supported. Conceptually, the I²C interface allows access to the Si1132 internal registers. Table 11 on page 24 is a summary of these registers.

An I²C write access always begins with a start (or restart) condition. The first byte after the start condition is the I²C address and a read-write bit. The second byte specifies the starting address of the Si1132 internal register. Subsequent bytes are written to the Si1132 internal register sequentially until a stop condition is encountered. An I²C write access with only two bytes is typically used to set up the Si1132 internal address in preparation for an I²C read.

The I²C read access, like the I²C write access, begins with a start or restart condition. In an I²C read, the I²C master then continues to clock SCL to allow the Si1132 to drive the I²C with the internal register contents.

The Si1132 also supports burst reads and burst writes. The burst read is useful in collecting contiguous, sequential registers. The Si1132 register map was designed to optimize for burst reads for interrupt handlers, and the burst writes are designed to facilitate rapid programming of commonly used fields.

The internal register address is a six-bit (bit 5 to bit 0) plus an Autoincrement Disable (on bit 6). The Autoincrement Disable is turned off by default. Disabling the autoincrementing feature allows the host to poll any single internal register repeatedly without having to keep updating the Si1132 internal address every time the register is read.

It is recommended that the host should read measurements (in the I²C Register Map) when the Si1132 asserts INT. Although the host can read any of the Si1132's I²C registers at any time, care must be taken when reading 2-byte measurements outside the context of an interrupt handler. The host could be reading part of the 2-byte measurement when the internal sequencer is updating that same measurement coincidentally. When this happens, the host could be reading a hybrid 2-byte quantity whose high byte and low byte are parts of different samples. If the host must read these 2-byte registers outside the context of an interrupt handler, the host should "double-check" a measurement if the measurement deviates significantly from a previous reading.

I²C Broadcast Reset: The I²C Broadcast Reset should be sent prior to any I²C register access to the Si1132. If any I²C register or parameter has already been written to the Si1132 when the I²C Broadcast Reset is issued, the host must send a reset command and reinitialize the Si1132 completely.

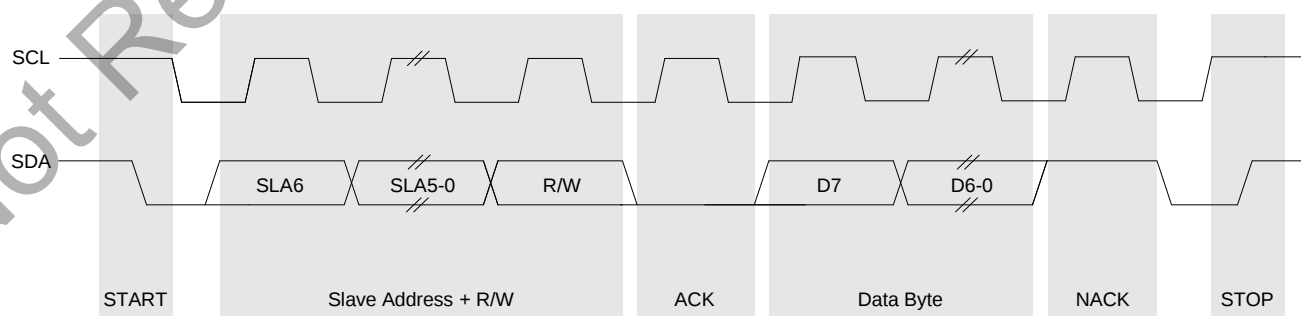


Figure 8. I²C Bit Timing Diagram



Figure 9. Host Interface Single Write

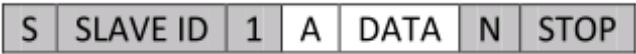


Figure 10. Host Interface Single Read



Figure 11. Host Interface Burst Write



Figure 12. Host Interface Burst Read

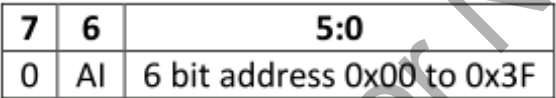


Figure 13. Si1132 REG ADDRESS Format

Notes:

- Gray boxes are driven by the host to the Si1132
- White boxes are driven by the Si1132 to the host
- A = ACK or “acknowledge”
- N = NACK or “no acknowledge”
- S = START condition
- Sr = repeat START condition
- P = STOP condition
- AI = Disable Auto Increment when set

3. Operational Modes

The Si1132 can be in one of many operational modes at any one time. It is important to consider the operational mode since the mode has an impact on the overall power consumption of the Si1132. The various modes are:

- Off Mode
- Initialization Mode
- Standby Mode
- Forced Conversion Mode
- Autonomous Mode

3.1. Off Mode

The Si1132 is in the Off Mode when V_{DD} is either not connected to a power supply or if the V_{DD} voltage is below the stated V_{DD_OFF} voltage described in the electrical specifications. As long as the parameters stated in Table 4, “Absolute Maximum Limits,” on page 7 are not violated, no current will flow through the Si1132. In the Off Mode, the Si1132 SCL and SDA pins do not interfere with other I²C devices on the bus. Keeping V_{DD} less than V_{DD_OFF} is not intended as a method of achieving lowest system current draw. The reason is that the ESD protection devices on the SCL, SDA and INT pins also form a current path through V_{DD} . If V_{DD} is grounded for example, then, current flow from system power to system ground through the SCL, SDA and INT pull-up resistors and the ESD protection devices.

Allowing V_{DD} to be less than V_{DD_OFF} is intended to serve as a hardware method of resetting the Si1132 without a dedicated reset pin.

The Si1132 can also reenter the Off Mode upon receipt of either a general I²C reset or if a software reset sequence is initiated. When one of these software methods is used to enter the Off Mode, the Si1132 typically proceeds directly from the Off Mode to the Initialization Mode.

3.2. Initialization Mode

When power is applied to V_{DD} and is greater than the minimum V_{DD} Supply Voltage stated in Table 1, “Recommended Operating Conditions,” on page 4, the Si1132 enters its Initialization Mode. In the Initialization Mode, the Si1132 performs its initial startup sequence. Since the I²C may not yet be active, it is recommended that no I²C activity occur during this brief Initialization Mode period. The “Start-up time” specification in Table 1 is the minimum recommended time the host needs to wait before sending any I²C accesses following a power-up sequence. After Initialization Mode has completed, the Si1132 enters Standby Mode. The host must write 0x17 to the HW_KEY register for proper operation.

3.3. Standby Mode

The Si1132 spends most of its time in Standby Mode. After the Si1132 completes the Initialization Mode sequence, it enters Standby mode. While in Standby Mode, the Si1132 does not perform any measurements. However, the I²C interface is active and ready to accept reads and writes to the Si1132 registers. The internal Digital Sequence Controller is in its sleep state and does not draw much power. In addition, the INT output retains its state until it is cleared by the host.

I²C accesses do not necessarily cause the Si1132 to exit the Standby Mode. For example, reading Si1132 registers is accomplished without needing the Digital Sequence Controller to wake from its sleep state.

3.4. Forced Conversion Mode

The Si1132 can operate in Forced Conversion Mode under the specific command of the host processor. The Forced Conversion Mode is entered if the ALS_FORCE command is sent. Upon completion of the conversion, the Si1132 can generate an interrupt to the host if the corresponding interrupt is enabled.

3.5. Autonomous Operation Mode

The Si1132 can be placed in the Autonomous Operation Mode where measurements are performed automatically without requiring an explicit host command for every measurement. The ALS_AUTO command is used to place the Si1132 in the Autonomous Operation Mode.

The Si1132 updates the I²C registers for ALS automatically. Each measurement is allocated a 16-bit register in the I²C map. It is possible to operate the Si1132 without interrupts. When doing so, the host poll rate must be at least twice the frequency of the conversion rates for the host to always receive a new measurement. The host can also choose to be notified when these new measurements are available by enabling interrupts.

The conversion frequencies for the ALS measurements are set up by the host prior to the ALS_AUTO command.

4. Programming Guide

4.1. Command and Response Structure

All Si1132 I²C registers (except writes to the COMMAND register) are read or written without waking up the internal sequencer. A complete list of the I²C registers can be found in "4.5. I2C Registers" on page 24. In addition to the I²C Registers, RAM parameters are memory locations maintained by the internal sequencer. These RAM Parameters are accessible through a Command Protocol (see "4.6. Parameter RAM" on page 35). A complete list of the RAM Parameters can be found in "4.6. Parameter RAM" on page 35.

The Si1132 can operate either in Forced Measurement or Autonomous Mode. When in Forced Measurement mode, the Si1132 does not make any measurements unless the host specifically requests the Si1132 to do so via specific commands (refer to the Section 3.2). The CHLIST parameter needs to be written so that the Si1132 would know which measurements to make. The parameter MEAS_RATE, when zero, places the internal sequencer in Forced Measurement mode. When in Forced Measurement mode, the internal sequencer wakes up only when the host writes to the COMMAND register. The power consumption is lowest in Forced Measurement mode (MEAS_RATE = 0).

The Si1132 operates in Autonomous Operation mode when MEAS_RATE is non-zero. The MEAS_RATE represents the time interval at which the Si1132 wakes up periodically. Up to three measurements are made (ALS_VIS, ALS_IR and AUX) depending on which measurements are enabled via the upper bits of the CHLIST Parameter. All three measurements are made in the following sequence: ALS_VIS, ALS_IR and AUX.

The ALS Measurement group consists of the Visible Light Ambient Measurement (ALS_VIS), the Infrared Light Ambient Measurement (ALS_IR) and the Auxiliary measurement (AUX). Each measurement group has three measurements each. The Channel List (CHLIST) parameter enables the specific measurements for that measurement grouping.

Each measurement (ALS_VIS, ALS_IR, AUX) are controlled through a combination of I2C Register or Parameter RAM. Tables 7 to 9 below summarize the properties and resources used for each measurement.

4.2. Command Protocol

The I²C map implements a bidirectional message box between the host and the Si1132 Sequencer. Host-writable I²C registers facilitate host-to-Si1132 communication, while read-only I²C registers are used for Si1132-to-host communication.

Unlike the other host-writable I²C registers, the COMMAND register causes the internal sequencer to wake up from Standby mode to process the host request.

When a command is executed, the RESPONSE register is updated. Typically, when there is no error, the upper four bits are zeros. To allow command tracking, the lower four bits implement a 4-bit circular counter. In general, if the upper nibble of the RESPONSE register is non-zero, this indicates an error or the need for special processing.

The PARAM_WR and PARAM_RD registers are additional mailbox registers.

In addition to the registers in the I²C map, there are environmental parameters accessible through the Command/Response interface. These parameters are stored in the internal ram space. These parameters generally take more I²C accesses to read and write. The Parameter RAM is described in "4.6. Parameter RAM" on page 35.

For every write to the Command register, the following sequence is required:

1. Write 0x00 to Command register to clear the Response register.
2. Read Response register and verify contents are 0x00.
3. Write Command value from Table 5 into Command register.
4. Read the Response register and verify contents are now non-zero. If contents are still 0x00, repeat this step.

The Response register will be incremented upon the successful completion of a Command. If the Response register remains 0x00 for over 25 ms after the Command write, the entire Command process should be repeated from Step 1.

Step 4 above is not applicable to the Reset Command because the device will reset itself and does not increment the Response register after reset. No Commands should be issued to the device for at least 1 ms after a Reset is issued.

Table 5. Command Register Summary

COMMAND Register		PARAM_W R Register	PARAM_RD Register	Error Code in RESPONSE Register	Description
Name	Encoding				
PARAM_QUERY	100 aaaaa	—	nnnn nnnn	✓	Reads the parameter pointed to by bitfield [4:0] and writes value to PARAM_RD. See Table 12 for parameters.
PARAM_SET	101 aaaaa	dddd dddd	nnnn nnnn	✓	Sets parameter pointed by bitfield [4:0] with value in PARAM_WR, and writes value out to PARAM_RD. See Table 12 for parameters.
NOP	000 00000	—	—	✓	Forces a zero into the RESPONSE register
RESET	000 00001	—	—	✓	Performs a software reset of the firmware
BUSADDR	000 00010	—	—	—	Modifies I ² C address
Reserved	000 00011	—	—	—	—
Reserved	000 00100	—	—	—	—
Reserved	000 00101	—	—	—	—

Table 5. Command Register Summary (Continued)

COMMAND Register		PARAM_W R Register	PARAM_RD Register	Error Code in RESPONSE Register	Description
Name	Encoding				
GET_CAL	0001 0010	—	—		Reports calibration data to I ² C registers 0x22–0x2D
ALS_FORCE	000 00110	—	—	✓	Forces a single ALS measurement
Reserved	000 00111	—	—	—	—
Reserved	000 01000	—	—	—	—
Reserved	000 01001	—	—	—	—
ALS_PAUSE	000 01010	—	—	✓	Pauses autonomous ALS
Reserved	000 01011	—	—	—	—
Reserved	000 01100	—	—	✓	—
Reserved	000 01101	—	—	—	—
ALS_AUTO	000 01110	—	—	✓	Starts/Restarts an autonomous ALS Loop
Reserved	000 01111	—	—	—	—
Reserved	000 1xxxx	—	—	—	—

Table 6. Response Register Error Codes

RESPONSE Register	Description
0000 cccc	NO_ERROR. The lower bit is a circular counter and is incremented every time a command has completed. This allows the host to keep track of commands sent to the Si1132. The circular counter may be cleared using the NOP command.
1000 0000	INVALID_SETTING. An invalid setting was encountered. Clear using the NOP command.
1000 1100	ALS_VIS_ADC_OVERFLOW. Indicates visible ambient light channel conversion overflow.
1000 1101	ALS_IR_ADC_OVERFLOW. Indicates infrared ambient light channel conversion overflow.
1000 1110	AUX_ADC_OVERFLOW. Indicates auxiliary channel conversion overflow.

4.3. Resource Summary

Table 7. Resource Summary for Interrupts

Measurement Channel	Channel Enable	Interrupt Status Output	Interrupt Enable
ALS Visible	EN_ALS_VIS in CHLIST[4]	ALS_INT[1:0] in IRQ_ STATUS[1:0]	ALS_IE[1:0] in IRQ_ENABLE[1:0]
ALS IR	EN_ALS_IR in CHLIST[5]		
Auxiliary Measurement	EN_AUX in CHLIST[6]	—	—

Table 8. Resource Summary for ADC Parameters

Measurement Channel	ADC Output	ADC Input Source	ADC Recovery Count	ADC High Signal Mode	ADC Clock Divider	ADC Alignment
ALS Visible	ALS_VIS_DATA1 / ALS_VIS_DATA0		VIS_ADC_REC in ALS_VIS_ADC_COUNTER [6:4]	VIS_RANGE in ALS_VIS_ADC_MISC[5]	ALS_VIS_ ADC_GAIN [3:0]	ALS_VIS_ ALIGN in ALS_ ENCODING[4]
ALS IR	ALS_IR_DATA1[7:0] / ALS_IR_DATA0[7:0]		IR_ADC_REC in ALS_IR_ADC_COUNTER [6:4]	IR_RANGE in ALS_IR_ADC_MISC[5]	ALS_IR_ ADC_GAIN [3:0]	ALS_IR_ ALIGN in ALS_ ENCODING[5]
Auxiliary Measurement	AUX_DATA1[7:0] / AUX_DATA0[7:0]	AUX_ADCMUX[7:0]	—	—	—	—

Table 9. Resource Summary for Hardware Pins

Pin Name	Output Drive Disable	Analog Voltage Input Enable
INT	INT_OE in INT_CFG[0]	ANA_IN_KEY[31:0]

The interrupts of the Si1132 are controlled through the INT_CFG, IRQ_ENABLE, IRQ_MODE1, IRQ_MODE2 and IRQ_STATUS registers.

The INT hardware pin is enabled through the INT_OE bit in the INT_CFG register. The hardware essentially performs an AND function between the IRQ_ENABLE register and IRQ_STATUS register. After this AND function, if any bits are set, the INT pin is asserted. The host is responsible for clearing the interrupt by writing to the IRQ_STATUS register. When the specific bits of the IRQ_STATUS register is written with 1, that specific IRQ_STATUS bit is cleared.

Typically, the host software is expected to read the IRQ_STATUS register, stores a local copy, and then writes the same value back to the IRQ_STATUS to clear the interrupt source. The INT_CFG register is normally written with 1.

The IRQ_MODE1, IRQ_MODE2 and IRQ_ENABLE registers work together to define how the internal sequencer sets bits in the IRQ_STATUS register (and as a consequence, asserting the INT pin).

The ALS interrupts are described in Table 10.

Table 10. Ambient Light Sensing Interrupt Resources

IRQ_ENABLE[1:0]		Description
ALS_IE[1:0]		
0	0	No ALS Interrupts
0	1	ALS_INT set after every ALS_VIS or UV sample

4.4. Signal Path Software Model

The following diagram gives an overview of the signal paths, along with the I²C register and RAM Parameter bit fields that control them. Sections with detailed descriptions of the I²C registers and Parameter RAM follow.

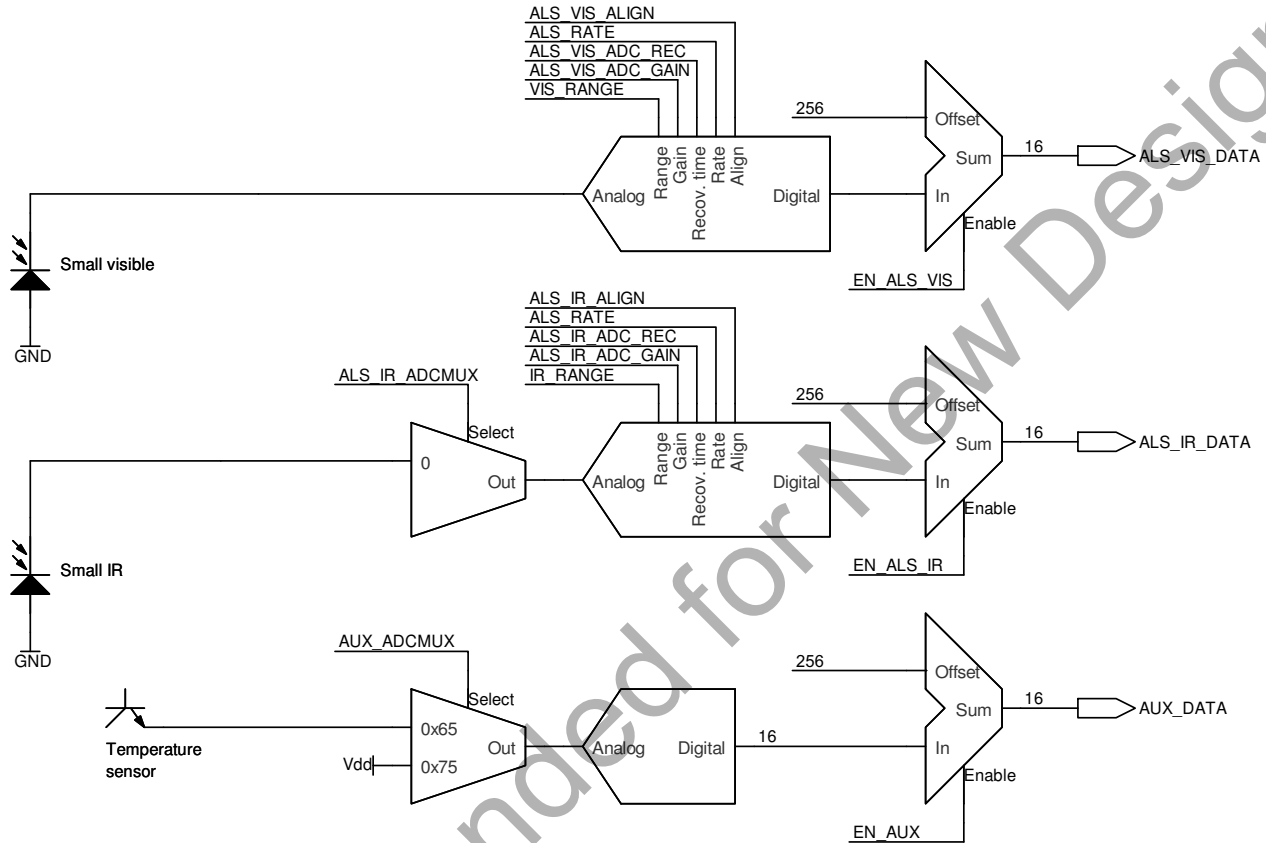


Figure 14. Signal Path Programming Model

4.5. I²C Registers

Table 11. I²C Register Summary

I ² C Register Name	Address	7	6	5	4	3	2	1	0	
PART_ID	0x00	PART_ID								
REV_ID	0x01	REV_ID								
SEQ_ID	0x02	SEQ_ID								
INT_CFG	0x03								INT_OE	
IRQ_ENABLE	0x04								ALS_IE	
HW_KEY	0x07	HW_KEY								
MEAS_RATE0	0x08	MEAS_RATE0								
MEAS_RATE1	0x09	MEAS_RATE1								
Reserved	0x0A									
Reserved	0x0B									
Reserved	0x0C									
Reserved	0x0D									
Reserved	0x0E									
Reserved	0x0F									
Reserved	0x10									
Reserved	0x11									
Reserved	0x12									
UCOEF0	0x13	UCOEF0								
UCOEF1	0x14	UCOEF1								
UCOEF2	0x15	UCOEF2								
UCOEF3	0x16	UCOEF3								
PARAM_WR	0x17	PARAM_WR								
COMMAND	0x18	COMMAND								
RESPONSE	0x20	RESPONSE								
IRQ_STATUS	0x21				CMD_INT				ALS_INT	
ALS_VIS_DATA0	0x22	ALS_VIS_DATA0								

Table 11. I²C Register Summary (Continued)

I ² C Register Name	Address	7	6	5	4	3	2	1	0
ALS_VIS_DATA1	0x23	ALS_VIS_DATA1							
ALS_IR_DATA0	0x24	ALS_IR_DATA0							
ALS_IR_DATA1	0x25	ALS_IR_DATA1							
Reserved	0x26								
Reserved	0x27								
Reserved	0x28								
Reserved	0x29								
Reserved	0x2A								
Reserved	0x2B								
AUX_DATA0/ UVINDEX0	0x2C	AUX_DATA0/UVINDEX0							
AUX_DATA1/ UVINDEX1	0x2D	AUX_DATA1/UVINDEX1							
PARAM_RD	0x2E	PARAM_RD							
CHIP_STAT	0x30						RUNNING	SUSPEND	SLEEP
ANA_IN_KEY	0x3B– 0x3E	ANA_IN_KEY							

Si1132

PART_ID @ 0x00

Bit	7	6	5	4	3	2	1	0
Name	PART_ID							
Type	R							

Reset value = 0011 0010

REV_ID @ 0x1

Bit	7	6	5	4	3	2	1	0
Name	REV_ID							
Type	R							

Reset value = 0000 0000

SEQ_ID @ 0x02

Bit	7	6	5	4	3	2	1	0
Name	SEQ_ID							
Type	R							

Reset value = 0000 1000

Bit	Name	Function
7:0	SEQ_ID	Sequencer Revision. 0x08 Si1132-A10 (MAJOR_SEQ=1, MINOR_SEQ=0)

INT_CFG @ 0x03

Bit	7	6	5	4	3	2	1	0
Name								INT_OE
Type	RW							RW

Reset value = 0000 0000

Bit	Name	Function
7:2	Reserved	Reserved.
0	INT_OE	INT Output Enable. INT_OE controls the INT pin drive 0: INT pin is never driven 1: INT pin driven low whenever an IRQ_STATUS and its corresponding IRQ_ENABLE bits match

IRQ_ENABLE @ 0x04

Bit	7	6	5	4	3	2	1	0
Name								ALS_IE
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:1	Reserved	Reserved.
0	ALS_IE	ALS Interrupt Enable. Enables interrupts when VIS bit or UV bit in CHLIST is enabled. 0: INT never asserts due to VIS or UV activity 1: Assert INT pin whenever VIS or UV measurements are ready

Si1132

HW_KEY @ 0x07

Bit	7	6	5	4	3	2	1	0
Name	HW_KEY							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	HW_KEY	The system must write the value 0x17 to this register for proper Si1132 operation.

MEAS_RATE0: MEAS_RATE Data Word Low Byte @ 0x08

Bit	7	6	5	4	3	2	1	0
Name	MEAS_RATE[7:0]							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	MEAS_RATE[7:0]	MEAS_RATE1 and MEAS_RATE0 together form a 16-bit value: MEAS_RATE [15:0]. The 16-bit value, when multiplied by 31.25 μs, represents the time duration between wake-up periods where measurements are made. Once the device wakes up, all measurements specified in CHLIST are made. Note that for the Si1132 with SEQ_ID=0x01, there is a code error that places MEAS_RATE0 at 0x0A with MEAS_RATE1 at 0x08 instead. This will be fixed in future revisions of the Si1132.

MEAS_RATE1: MEAS_RATE Data Word High Byte @ 0x09

Bit	7	6	5	4	3	2	1	0
Name	MEAS_RATE[15:8]							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	MEAS_RATE[15:8]	MEAS_RATE1 and MEAS_RATE0 together form a 16-bit value: MEAS_RATE[15:0]. The 16-bit value, when multiplied by 31.25 μ s, represents the time duration between wake-up periods where measurements are made. Once the device wakes up, all measurements specified in CHLIST are made. Note that for the Si1132 with SEQ_ID=0x01, there is a code error that places MEAS_RATE0 at 0x0A and MEAS_RATE1 at 0x08 instead. This will be fixed in future revisions of the Si1132.

PARAM_WR @ 0x17

Bit	7	6	5	4	3	2	1	0
Name	PARAM_WR							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	PARAM_WR	Mailbox register for passing parameters from the host to the sequencer.

COMMAND @ 0x18

Bit	7	6	5	4	3	2	1	0
Name	COMMAND							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	COMMAND	COMMAND Register. The COMMAND Register is the primary mailbox register into the internal sequencer. Writing to the COMMAND register is the only I ² C operation that wakes the device from standby mode.

RESPONSE @ 0x20

Bit	7	6	5	4	3	2	1	0
Name	RESPONSE							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	RESPONSE	The Response register is used in conjunction with command processing. When an error is encountered, the response register will be loaded with an error code. All error codes will have the MSB is set. The error code is retained until a RESET or NOP command is received by the sequencer. Other commands other than RESET or NOP will be ignored. However, any autonomous operation in progress continues normal operation despite any error. 0x00–0x0F: No Error. Bits 3:0 form an incrementing roll-over counter. The roll over counter in bit 3:0 increments when a command has been executed by the Si1132. Once autonomous measurements have started, the execution timing of any command becomes non-deterministic since a measurement could be in progress when the COMMAND register is written. The host software must make use of the rollover counter to ensure that commands are processed. 0x80: Invalid Command Encountered during command processing 0x8C: ADC Overflow encountered during ALS-VIS measurement 0x8D: ADC Overflow encountered during ALS-IR measurement 0x8E: ADC Overflow encountered during AUX measurement

IRQ_STATUS @ 0x21

Bit	7	6	5	4	3	2	1	0
Name			CMD_INT					ALS_INT
Type	RW						RW	

Reset value = 0000 0000

Bit	Name	Function
7:6	Reserved	Reserved.
5	CMD_INT	Command Interrupt Status.
4:2	Reserved	Reserved.
1:0	ALS_INT	ALS Interrupt Status. (Refer to Table 13 for encoding.)

Note: If the corresponding IRQ_ENABLE bit is also set when the IRQ_STATUS bit is set, the INT pin is asserted.**ALS_VIS_DATA0: ALS_VIS_DATA Data Word Low Byte @ 0x22**

Bit	7	6	5	4	3	2	1	0
Name	ALS_VIS_DATA[7:0]							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	ALS_VIS_DATA[7:0]	ALS VIS Data LSB. Once autonomous measurements have started, this register must be read after INT has asserted but before the next measurement is made. Refer to “AN498: Si114x Designer’s Guide”, section “5.6.2 Host Interrupt Latency”.

ALS_VIS_DATA1: ALS_VIS_DATA Data Word High Byte @ 0x23

Bit	7	6	5	4	3	2	1	0
Name	ALS_VIS_DATA[15:8]							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	ALS_VIS_DATA[15:8]	ALS VIS Data MSB. Once autonomous measurements have started, this register must be read after INT has asserted but before the next measurement is made. Refer to “AN498: Si114x Designer’s Guide”, section “5.6.2 Host Interrupt Latency”.

ALS_IR_DATA0: ALS_IR_DATA Data Word Low Byte @ 0x24

Bit	7	6	5	4	3	2	1	0
Name	ALS_IR_DATA[7:0]							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	ALS_IR_DATA[7:0]	ALS IR Data LSB. Once autonomous measurements have started, this register must be read after INT has asserted but before the next measurement is made. Refer to “AN498: Si114x Designer’s Guide”, section “5.6.2 Host Interrupt Latency”.

ALS_IR_DATA1: ALS_IR_DATA Data Word High Byte @ 0x25

Bit	7	6	5	4	3	2	1	0
Name	ALS_IR_DATA[15:8]							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	ALS_IR_DATA[15:8]	ALS IR Data MSB. Once autonomous measurements have started, this register must be read after INT has asserted but before the next measurement is made. Refer to “AN498: Si114x Designer’s Guide”, section “5.6.2 Host Interrupt Latency”.

AUX_DATA0/UVINDEX0: AUX_DATA Data Word Low Byte @ 0x2C

Bit	7	6	5	4	3	2	1	0
Name	AUX_DATA[7:0]							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	AUX_DATA[7:0]	AUX Data LSB. Once autonomous measurements have started, this register must be read after INT has asserted but before the next measurement is made. Refer to “AN498: Si114x Designer’s Guide”, section “5.6.2 Host Interrupt Latency”.

AUX_DATA1/UVINDEX1: AUX_DATA Data Word High Byte @ 0x2D

Bit	7	6	5	4	3	2	1	0
Name	AUX_DATA[15:8]							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	AUX_DATA[15:8]	AUX Data MSB. Once autonomous measurements have started, this register must be read after INT has asserted but before the next measurement is made. Refer to “AN498: Si114x Designer’s Guide”, section “5.6.2 Host Interrupt Latency”.

PARAM_RD @ 0x2E

Bit	7	6	5	4	3	2	1	0
Name	PARAM_RD							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	PARAM_RD	Mailbox register for passing parameters from the sequencer to the host.

CHIP_STAT @ 0x30

Bit	7	6	5	4	3	2	1	0
Name						RUNNING	SUSPEND	SLEEP
Type				R			R	R

Reset value = 0000 0000

Bit	Name	Function
7:3	Reserved	Reserved
2	RUNNING	Device is awake.
1	SUSPEND	Device is in a low-power state, waiting for a measurement to complete.
0	SLEEP	Device is in its lowest power state.

ANA_IN_KEY @ 0x3B to 0x3E

Bit	7	6	5	4	3	2	1	0
0x3B	ANA_IN_KEY[31:24]							
0x3C	ANA_IN_KEY[23:16]							
0x3D	ANA_IN_KEY[15:8]							
0x3E	ANA_IN_KEY[7:0]							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
31:0	ANA_IN_KEY[31:0]	Reserved.

4.6. Parameter RAM

Parameters are located in internal memory and are not directly addressable over I²C. They must be indirectly accessed using the PARAM_QUERY and PARAM_SET commands described in "4.2. Command Protocol" on page 18.

Table 12. Parameter RAM Summary Table

Parameter Name	Offset	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
I2C_ADDR	0x00	I ² C Address							
CHLIST	0x01	EN_UV	EN_AUX	EN_ALS_IR	EN_ALS_VIS				
Reserved	0x02								
Reserved	0x03								
Reserved	0x04	Reserved (always set to 0)							
Reserved	0x05					Reserved (always set to 0)			
ALS_ENCODING	0x06			ALS_IR_ALIGN	ALS_VIS_ALIGN	Reserved (always set to 0)			
Reserved	0x07								
Reserved	0x08								
Reserved	0x09								
Reserved	0x0A								
Reserved	0x0B								
Reserved	0x0C								
Reserved	0x0D	Reserved (do not modify from default setting of 0x02)							
ALS_IR_ADCMUX	0x0E	ALS_IR_ADCMUX							
AUX_ADCMUX	0x0F	AUX ADC Input Selection							
ALS_VIS_ADC_COUNTER	0x10		VIS_ADC_REC				Reserved (always set to 0)		
ALS_VIS_ADC_GAIN	0x11							ALS_VIS_ADC_GAIN	
ALS_VIS_ADC_MISC	0x12	Reserved (always set to 0)		VIS_RANGE	Reserved (always set to 0)				
Reserved	0x13	Reserved (do not modify from default setting of 0x40)							
Reserved	0x14–0x15	Reserved (do not modify from default setting of 0x00)							
Reserved	0x1B	Reserved (do not modify from default setting of 0x00)							
Reserved	0x1C								
ALS_IR_ADC_COUNTER	0x1D		IR_ADC_REC				Reserved (always set to 0)		
ALS_IR_ADC_GAIN	0x1E							ALS_IR_ADC_GAIN	
ALS_IR_ADC_MISC	0x1F	Reserved (always set to 0)		IR_RANGE	Reserved (always set to 0)				

I2C @ 0x00

Bit	7	6	5	4	3	2	1	0
Name	I ² C Address[7:0]							
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:0	I ² C Address[7:0]	Specifies a new I ² C Address for the device to respond to. The new address takes effect when a BUSADDR command is received.

CHLIST @ 0x01

Bit	7	6	5	4	3	2	1	0
Name	EN_UV	EN_AUX	EN_ALS_IR	EN_ALS_VIS				
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7	EN_UV	Enables UV Index, data stored in AUX_DATA1[7:0] and AUX_DATA0[7:0]
6	EN_AUX	Enables Auxiliary Channel, data stored in AUX_DATA1[7:0] and AUX_DATA0[7:0].
5	EN_ALS_IR	Enables ALS IR Channel, data stored in ALS_IR_DATA1[7:0] and ALS_IR_DATA0[7:0].
4	EN_ALS_VIS	Enables ALS Visible Channel, data stored in ALS_VIS_DATA1[7:0] and ALS_VIS_DATA0[7:0].
3:0	Reserved	
Note: For proper operation, CHLIST must be written with a non-zero value before forced measurements or autonomous operation is requested.		

ALS_ENCODING @ 0x06

Bit	7	6	5	4	3	2	1	0
Name			ALS_IR_ALIGN	ALS_VIS_ALIGN				
Type	RW		RW					

Reset value = 0000 0000

Bit	Name	Function
7:6	Reserved	
5	ALS_IR_ALIGN	When set, the ADC reports the least significant 16 bits of the 17-bit ADC when performing ALS VIS Measurement. Reports the 16 MSBs when cleared.
4	ALS_VIS_ALIGN	When set, the ADC reports the least significant 16 bits of the 17-bit ADC when performing ALS IR Measurement. Reports the 16 MSBs when cleared.
3:0	Reserved	Always set to 0.

ALS_IR_ADCMUX @ 0x0E

Bit	7	6	5	4	3	2	1	0
Name	ALS_IR_ADCMUX							
Type	RW							

Bit	Name	Function
7:0	ALS_IR_ADCMUX	Selects ADC Input for ALS_IR Measurement. 0x00: Small IR photodiode

AUX_ADCMUX @ 0x0F

Bit	7	6	5	4	3	2	1	0
Name	AUX_ADCMUX[7:0]							
Type	RW							

Reset value = 0110 0101

Bit	Name	Function
7:0	AUX_ADCMUX[7:0]	Selects input for AUX Measurement. These measurements are referenced to GND. 0x65: Temperature (Should be used only for relative temperature measurement. Absolute Temperature not guaranteed) 0x75: V _{DD} voltage

ALS_VIS_ADC_COUNTER @ 0x10

Bit	7	6	5	4	3	2	1	0
Name		VIS_ADC_REC[2:0]						
Type		RW	R/W	R/W				

Reset value = 0111 0000

Bit	Name	Function
7	Reserved	
6:4	VIS_ADC_REC[2:0]	Recovery period the ADC takes before making a ALS-VIS measurement. 000: 1 ADC Clock (50 ns times 2 ^{ALS_VIS_ADC_GAIN}) 001: 7 ADC Clock (350 ns times 2 ^{ALS_VIS_ADC_GAIN}) 010: 15 ADC Clock (750 ns times 2 ^{ALS_VIS_ADC_GAIN}) 011: 31 ADC Clock (1.55 µs times 2 ^{ALS_VIS_ADC_GAIN}) 100: 63 ADC Clock (3.15 µs times 2 ^{ALS_VIS_ADC_GAIN}) 101: 127 ADC Clock (6.35 µs times 2 ^{ALS_VIS_ADC_GAIN}) 110: 255 ADC Clock (12.75 µs times 2 ^{ALS_VIS_ADC_GAIN}) 111: 511 ADC Clock (25.55 µs times 2 ^{ALS_VIS_ADC_GAIN}) The recommended VIS_ADC_REC value is the one's complement of ALS_VIS_ADC_GAIN.
3:0	Reserved	Always set to 0.

ALS_VIS_ADC_GAIN @ 0x11

Bit	7	6	5	4	3	2	1	0
Name						ALS_VIS_ADC_GAIN[2:0]		
Type	RW			R/W		RW		

Reset value = 0000 0000

Bit	Name	Function
7:3	Reserved	
2:0	ALS_VIS_ADC_GAIN[2:0]	Increases the ADC integration time for ALS Visible measurements by a factor of $(2^{\text{ALS_VIS_ADC_GAIN}})$. This allows visible light measurement under dark glass. The maximum gain is 128 (0x7). For Example: 0x0: ADC Clock is divided by 1 0x4: ADC Clock is divided by 16 0x6: ADC Clock is divided by 64

ALS_VIS_ADC_MISC @ 0x12

Bit	7	6	5	4	3	2	1	0
Name			VIS_RANGE					
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:6	Reserved	
5	VIS_RANGE	When performing ALS-VIS measurements, the ADC can be programmed to operate in high sensitivity operation or high signal range. The high signal range is useful in operation under direct sunlight. 0: Normal Signal Range 1: High Signal Range (Gain divided by 14.5)
4:0	Reserved	

ALS_IR_ADC_COUNTER @ 0x1D

Bit	7	6	5	4	3	2	1	0
Name		IR_ADC_REC[2:0]						
Type	RW							

Reset value = 0111 0000

Bit	Name	Function
7	Reserved	
6:4	IR_ADC_REC[2:0]	Recovery period the ADC takes before making a ALS-IR measurement. 000: 1 ADC Clock (50 ns times $2^{\text{ALS_IR_ADC_GAIN}}$) 001: 7 ADC Clock (350 ns times $2^{\text{ALS_IR_ADC_GAIN}}$) 010: 15 ADC Clock (750 ns times $2^{\text{ALS_IR_ADC_GAIN}}$) 011: 31 ADC Clock (1.55 μs times $2^{\text{ALS_IR_ADC_GAIN}}$) 100: 63 ADC Clock (3.15 μs times $2^{\text{ALS_IR_ADC_GAIN}}$) 101: 127 ADC Clock (6.35 μs times $2^{\text{ALS_IR_ADC_GAIN}}$) 110: 255 ADC Clock (12.75 μs times $2^{\text{ALS_IR_ADC_GAIN}}$) 111: 511 ADC Clock (25.55 μs times $2^{\text{ALS_IR_ADC_GAIN}}$) The recommended IR_ADC_REC value is the one's complement of ALS_IR_ADC_GAIN.
3:0	Reserved	Always set to 0.

ALS_IR_ADC_GAIN @ 0x1E

Bit	7	6	5	4	3	2	1	0
Name						ALS_IR_ADC_GAIN[2:0]		
Type						R/W	R/W	R/W

Reset value = 0000 0000

Bit	Name	Function
7:3	Reserved	
2:0	ALS_IR_ADC_GAIN[2:0]	Increases the ADC integration time for IR Ambient measurements by a factor of $(2^{\text{ALS_IR_ADC_GAIN}})$. The maximum gain is 128 (0x7). For Example: 0x0: ADC Clock is divided by 1 0x4: ADC Clock is divided by 16 0x6: ADC Clock is divided by 64

ALS_IR_ADC_MISC @ 0x1F

Bit	7	6	5	4	3	2	1	0
Name			IR_RANGE					
Type	RW							

Reset value = 0000 0000

Bit	Name	Function
7:6	Reserved	
5	IR_RANGE	When performing ALS-IR measurements, the ADC can be programmed to operate in high sensitivity operation or high signal range. The high signal range is useful in operation under direct sunlight. 0: Normal Signal Range 1: High Signal Range (Gain divided by 14.5)
4:0	Reserved	Write operations to this RAM parameter must preserve this bit-field value using read-modify-write.

5. Pin Descriptions

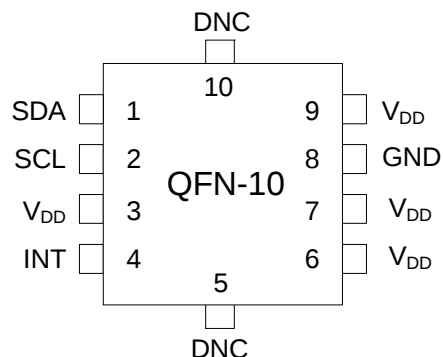


Table 13. Pin Descriptions

Pin	Name	Type	Description
1	SDA	Bidirectional	I ² C Data.
2	SCL	Input	I ² C Clock.
3	V _{DD}	Power	Power Supply. Voltage source.
4	INT	Bidirectional	Interrupt Output. Open-drain interrupt output pin. Must be at logic level high during power-up sequence to enable low power operation.
5	DNC		Do Not Connect. This pin is electrically connected to an internal Si1132 node. It should remain unconnected.
6	V _{DD}	Power	Power Supply. Voltage source.
7	V _{DD}	Power	Power Supply. Voltage source.
8	GND	Power	Ground. Reference voltage.
9	V _{DD}	Power	Power Supply. Voltage source.
10	DNC		Do Not Connect. This pin is electrically connected to an internal Si1132 node. It should remain unconnected.

6. Ordering Guide

Part Number	Package
Si1132-A10-GMR	QFN-10

Not Recommended for New Designs

7. Package Outline: 10-Pin QFN

Figure 15 illustrates the package details for the Si1132 QFN package. Table 14 lists the values for the dimensions shown in the illustration.

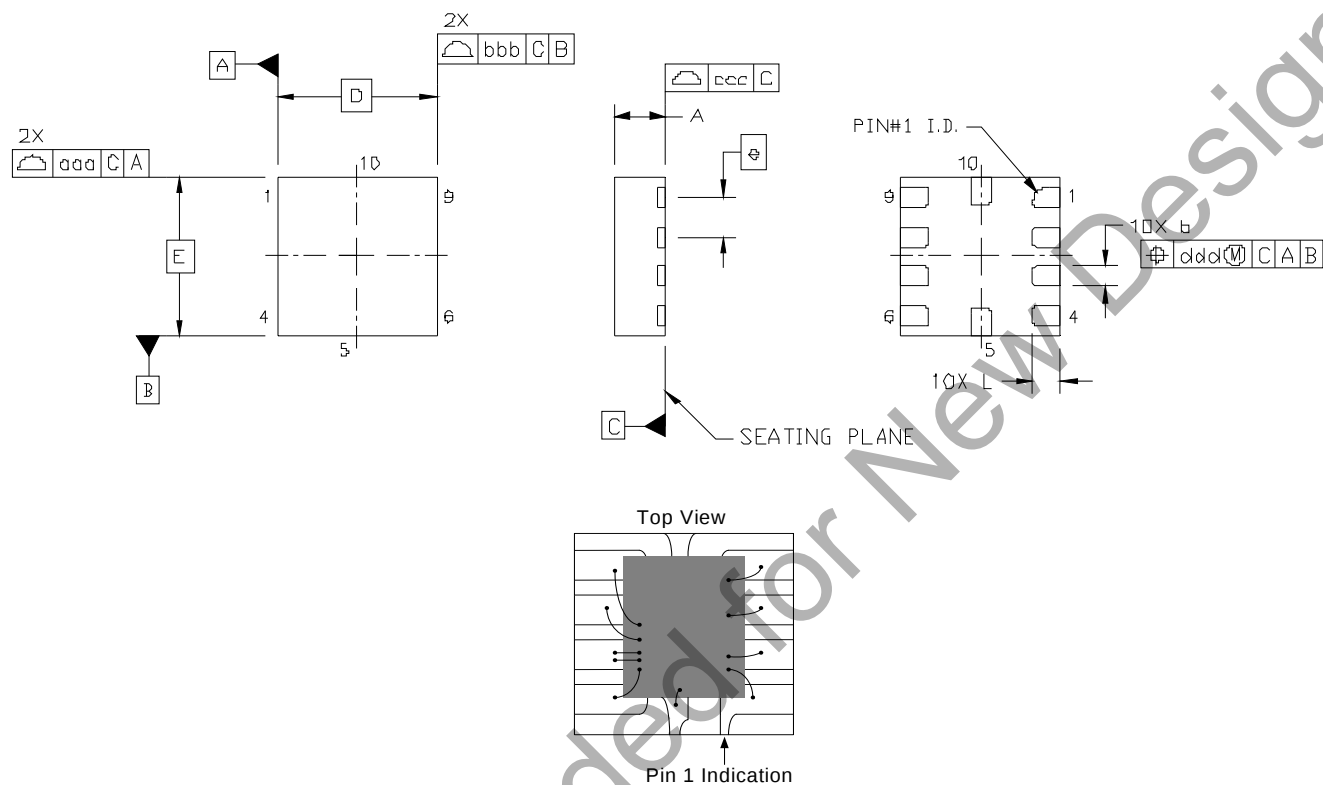


Figure 15. QFN Package Diagram Dimensions

Table 14. Package Diagram Dimensions

Dimension	Min	Nom	Max
A	0.55	0.65	0.75
b	0.20	0.25	0.30
D	2.00 BSC.		
e	0.50 BSC.		
E	2.00 BSC.		
L	0.30	0.35	0.40
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.10		
Notes:			
1. All dimensions shown are in millimeters (mm).			
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.			

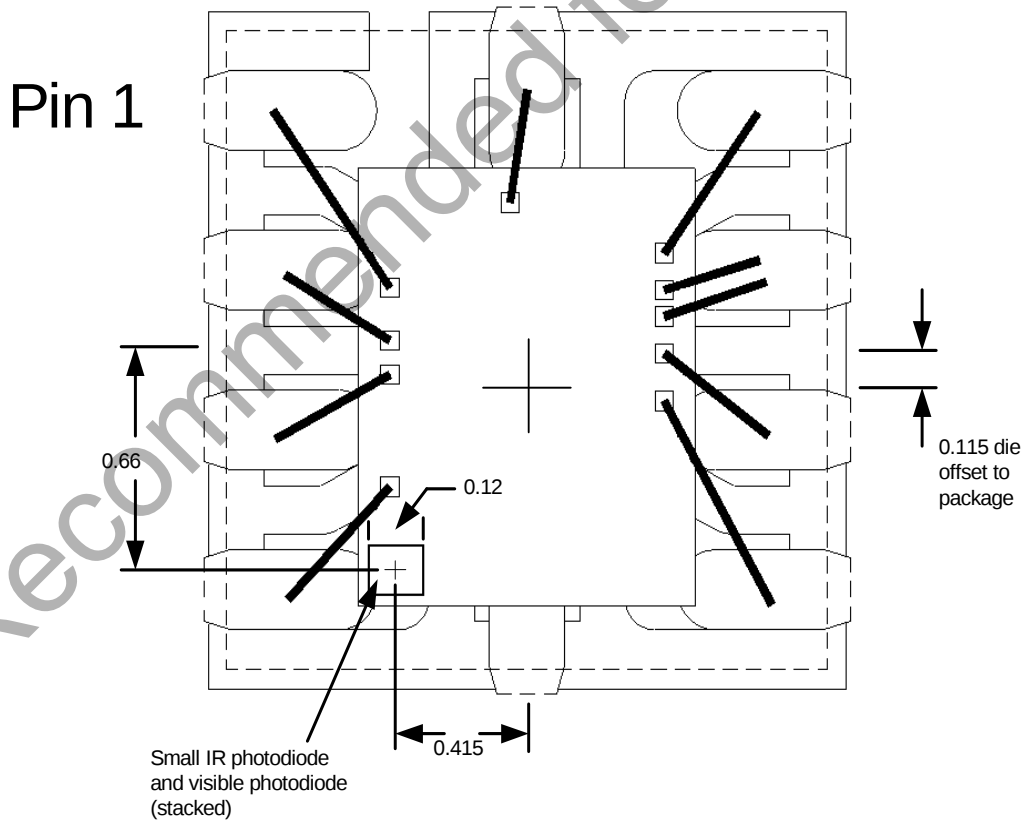


Figure 16. Photodiode Centers

8. Suggested PCB Land Pattern

Figure 17 illustrates the PCB land pattern details for the Si1132. Table 15 lists the values for the dimensions shown in the illustration.

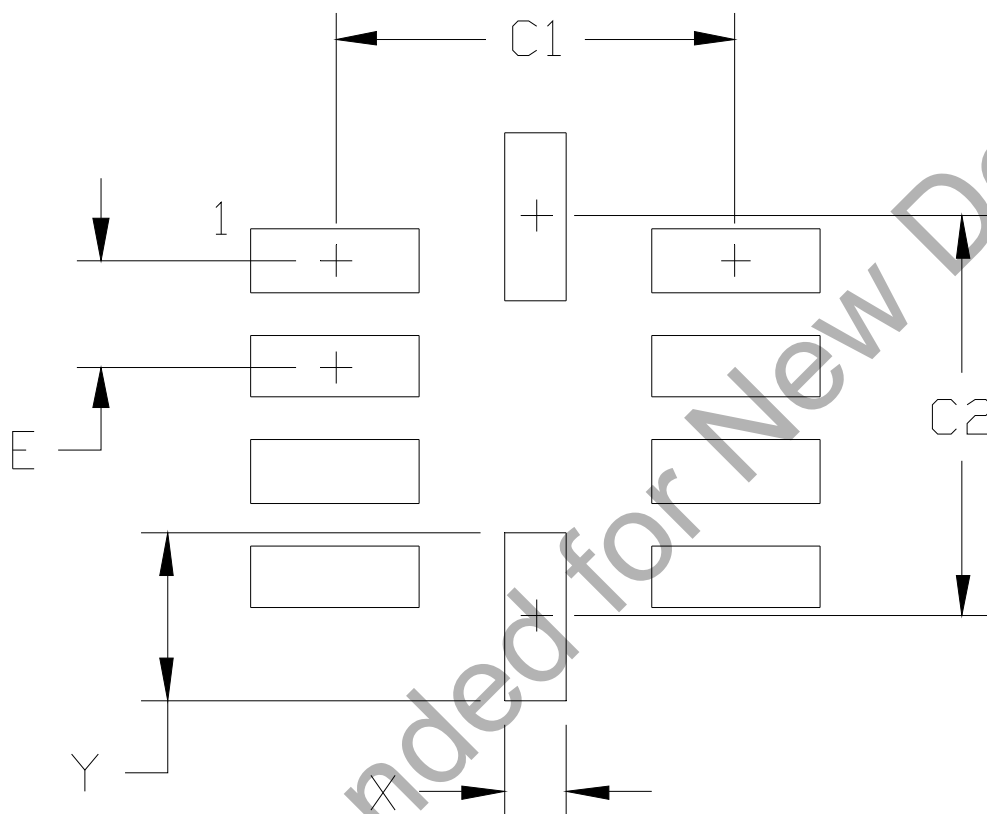


Figure 17. PCB Land Pattern

Table 15. PCB Land Pattern Dimensions

Dimension	mm
C1	1.90
C2	1.90
E	0.50
X	0.30
Y	0.80

Notes:**General**

1. All dimensions shown are in millimeters (mm).
2. This Land Pattern Design is based on the IPC-7351 guidelines.
3. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

4. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 mm minimum, all the way around the pad.

Stencil Design

5. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
6. The stencil thickness should be 0.125 mm (5 mils).
7. The ratio of stencil aperture to land pad size should be 1:1 for all pads.

Card Assembly

8. A No-Clean, Type-3 solder paste is recommended.
9. The recommended card reflow profile is per the JEDEC/IPC J-STD-020D specification for Small Body Components.

DOCUMENT CHANGE LIST

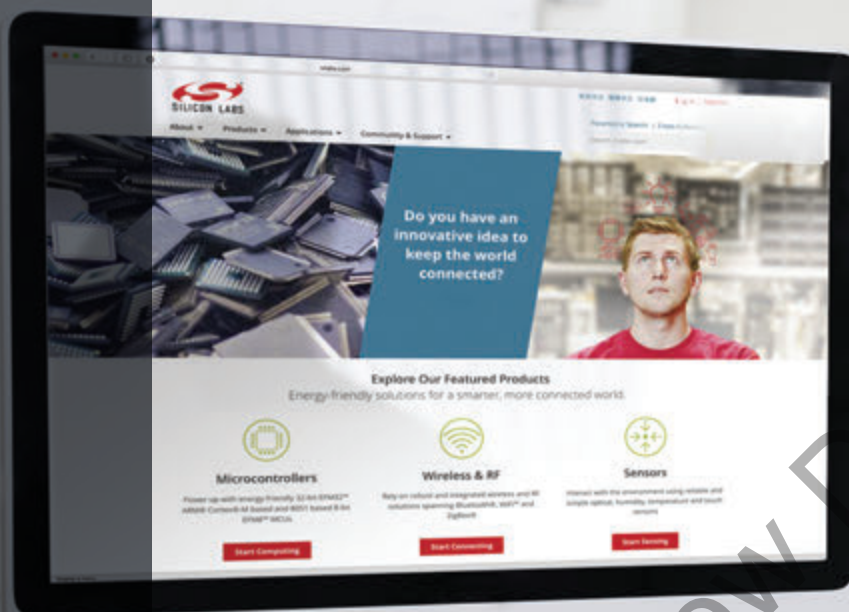
Revision 1.0 to Revision 1.1

- Updated recommended UV coefficients.
- Updated photodiode spectral response.

Revision 1.1 to Revision 1.2

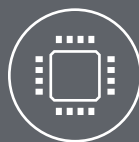
- Clarified usage of Command Register and Parameter RAM.
- Clarified how to enable UV Index.
- Corrected typo in description of MEAS_RATE1.

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